

CLAIM AMENDMENTS:

Claims 1-6 (Canceled).

Claim 7 (Currently Amended): A semiconductor device, comprising:

a semiconductor chip having a first semiconductor chip surface and a second semiconductor chip surface disposed opposite the first semiconductor chip surface, the second semiconductor chip surface defining a semiconductor chip surface area;

a wiring board having a wiring board thickness and being electrically connected to the semiconductor chip at the first semiconductor chip surface; and

a warp preventing board having a warp preventing board thickness and a warp preventing board surface defining a warp preventing board surface area,

wherein the warp preventing board surface and the second semiconductor chip surface are connected with each other in a face-to-face arrangement ~~contact with each other~~ so that the warp preventing board surface area of the warp preventing board surface covers the semiconductor chip surface area of the semiconductor chip,

wherein the warp preventing board thickness is substantially equal to the wiring board thickness, and the warp preventing board and the wiring board are fabricated from an identical material,

wherein the warp preventing board has a coefficient of thermal expansion that is essentially equal to a coefficient of thermal expansion of the wiring board,

wherein the semiconductor chip has a coefficient of thermal expansion that is different from the coefficient of thermal expansion of the warp preventing board and the wiring board, and

wherein the warp preventing board and the wiring board collectively cause any thermal expansion and thermal contraction to occur essentially equally on both the first semiconductor chip surface and a second semiconductor chip surface, thereby preventing warpage of the semiconductor chip during a change in an environmental temperature.